

Appl. No.: 10/707,927
Amdt. Dated: 1/8/2006
Reply to Office action of: 10/28/2005

AMENDMENTS TO THE SPECIFICATION:

Kindly add the following new paragraph after paragraph [0018]:
[0018.1] Figure 4 shows a partial plan view of the printed circuit board having both a substrate and a plurality of conductive tracks adhered thereto.

Kindly replace paragraph [0019] with the following amended paragraph:
[0019] § The multiple-milling process for manufacturing printed circuits shown in this preferred embodiment form is basically constituted by a process for preparing the board substrate 5 of the printed circuits 1 for the production of bending areas 2 from whence to bend the copper conductive layer 6 of said printed circuits 1. The conductive layer 6 has a thickness of 105 microns, although it can vary between 65 and 400 microns.

Kindly replace paragraph [0020] with the following amended paragraph:
[0020] This process consists of a multiple-milling system, by means of a mill 3 with special features, comprised of a roll provided with a multitude of polishing strips or teeth on the surface thereof, capable of performing an undercutting in the shape of parallel strips 4 in said bending areas 2 of a printed circuit 1, allowing for its subsequent bending without deteriorating the conductive copper tracks 6 adhered to the printed circuit's substrate on the side opposite the milled surface.

Kindly replace paragraph [0021] with the following amended paragraph:
[0021] The mill 3 acts on the conductive copper layer's support substrate 1 by removing material in multiple parallel strips 4 until the final substrate thickness which allows for bending the 105 micron, conductive copper layer 6 up to 180° is reached, preventing its breakage.